

L Number	Hits	Search Text	DB	Time stamp
1	1	reinforced adj semiconductor adj interconnect adj structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:38
2	3	reinforced adj interconnect adj structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:40
3	15	reinforced adj interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:41
4	72	reinforced adj via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:43
5	56	reinforced adj plug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:44
6	7	reinforced adj semiconductor adj (device or structure or portion or element)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:45
7	39	reinforced adj semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:46
8	638	semiconductor adj supports	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:46
9	73	semiconductor adj support adj structures	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:48
10	9	semiconductor adj support adj elements	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:49
11	7	semiconductor adj support adj (region or area or potion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:49
12	11	semiconductor adj support adj (region or area or portion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 11:51
13	150	(multilevel adj metallization) and (supports or reinforcements)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 12:00
14	56	(plurality adj metallization) and (supports or reinforcements)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/15 12:10

15	202	(plurality adj metal adj (layers or films)) and (supports or reinforcements)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/15 12:13
16	45	(first adj metal adj interconnect) and (supports or reinforcements)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/15 12:16
17	283	first adj metal adj interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/15 12:21
18	62	plurality adj metal adj interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/15 12:22
19	36	multiple adj metal adj interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/15 12:24
20	87	multilevel adj metal adj interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/15 12:24